

# SOT810-1

plastic thermal enhanced shrink small outline package; no leads; 18 terminals; body 8 x 12 x 2.1 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	HSSON18
<b>Package type industry code</b>	HSSON18
<b>Package style descriptive code</b>	HSSON (thermal enhanced shrink small outline; no leads)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	4-4-2005

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	11.85	-	12	12.15	mm
E	package width	7.85	-	8	8.15	mm
A	seated height	[tbd]	-	2.1	2.2	mm
A <sub>2</sub>	package height	[tbd]	-	2.1	[tbd]	mm
n <sub>2</sub>	actual quantity of termination	-	-	18	-	

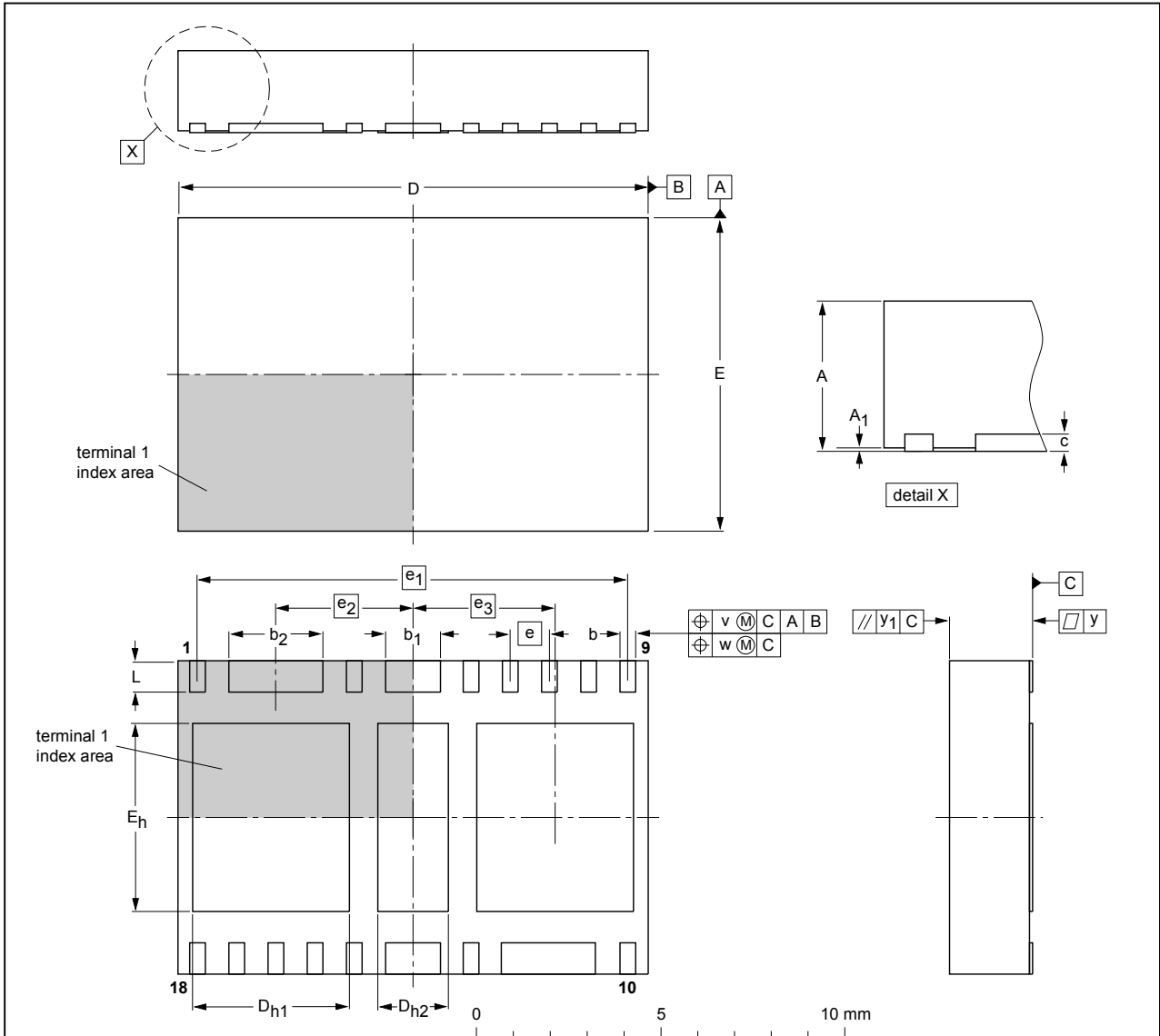


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## 2. Package outline

HSSON18: plastic thermal enhanced shrink small outline package; no leads; 18 terminals; body 8 x 12 x 2.1 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A <sup>(1)</sup> max.	A <sub>1</sub>	b	b <sub>1</sub>	b <sub>2</sub>	c	D <sup>(1)</sup>	D <sub>h1</sub>	D <sub>h2</sub>	E <sup>(1)</sup>	E <sub>h</sub>	e	e <sub>1</sub>	e <sub>2</sub>	e <sub>3</sub>	L	v	w	y	y <sub>1</sub>
mm	2.2	0.05 0.00	0.5 0.3	1.5 1.3	2.5 2.3	0.5	12.15 11.85	4.2 3.8	2.0 1.6	8.15 7.85	4.9 4.7	1	11	3.5	3.6	0.9 0.7	0.1	0.05	0.05	0.1

**Note**

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT810-1	---	---	---		04-07-20 05-04-04

Fig. 1. Package outline HSSON18 (SOT810-1)

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### 3. Soldering

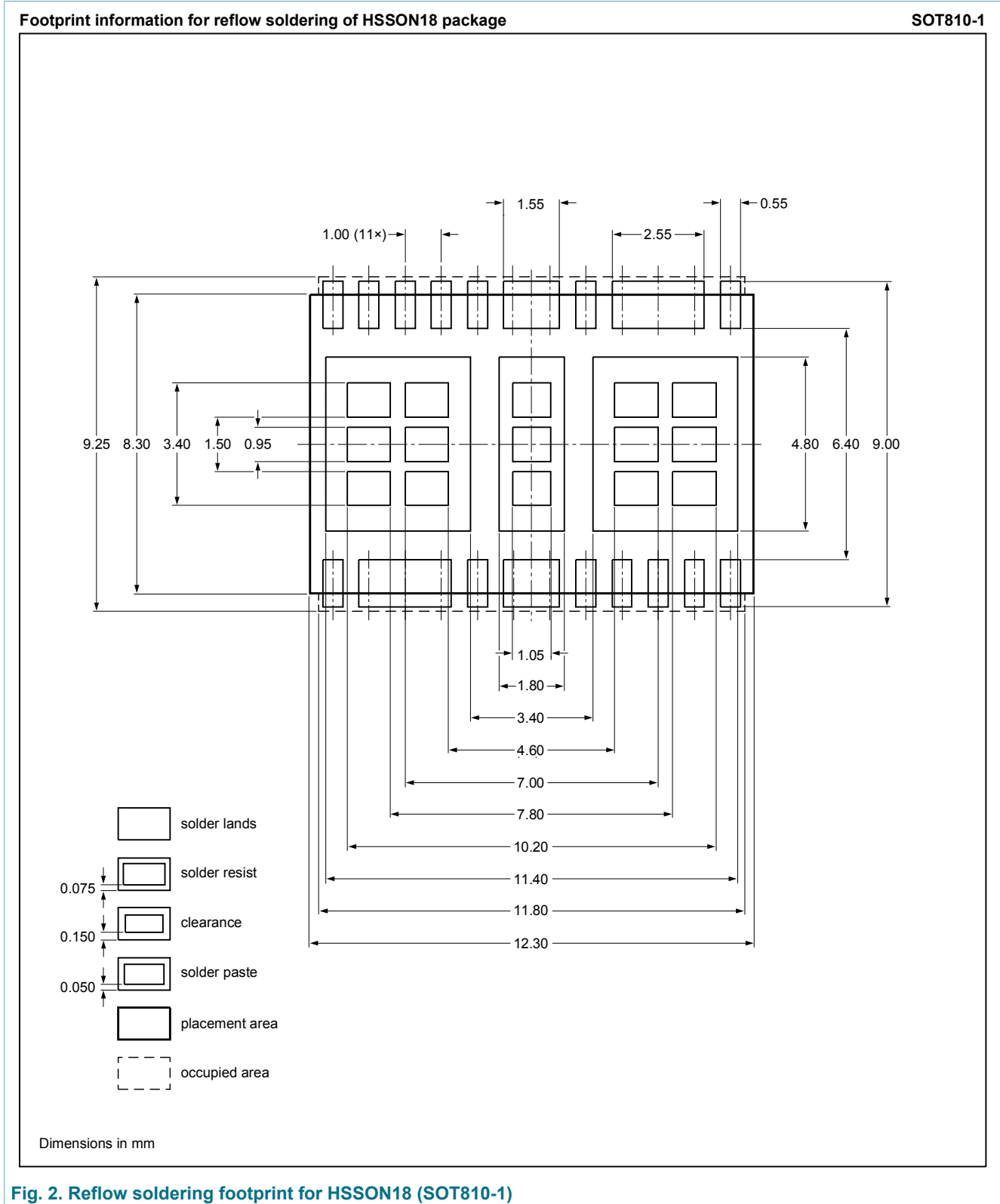


Fig. 2. Reflow soldering footprint for HSSON18 (SOT810-1)

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## 4. Legal information

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